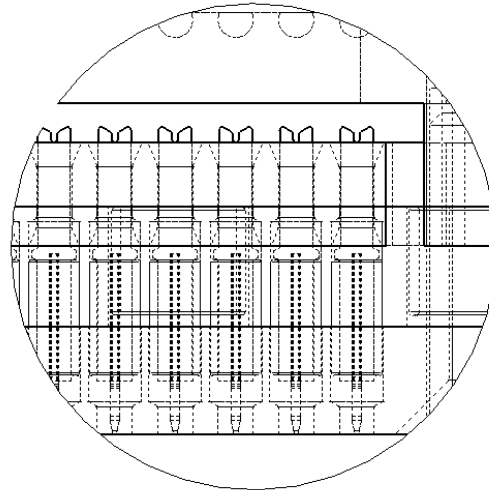
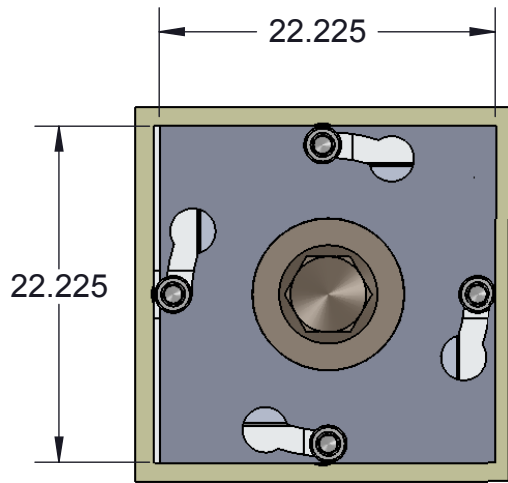
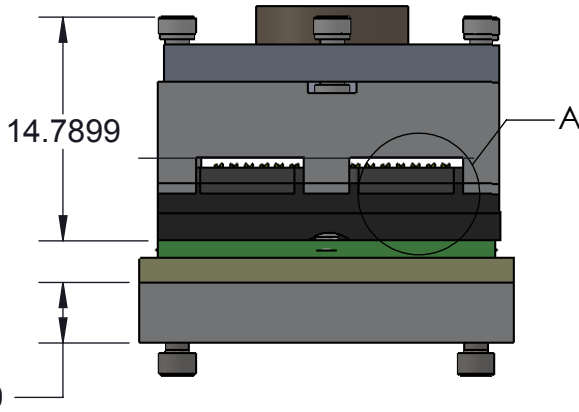


SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

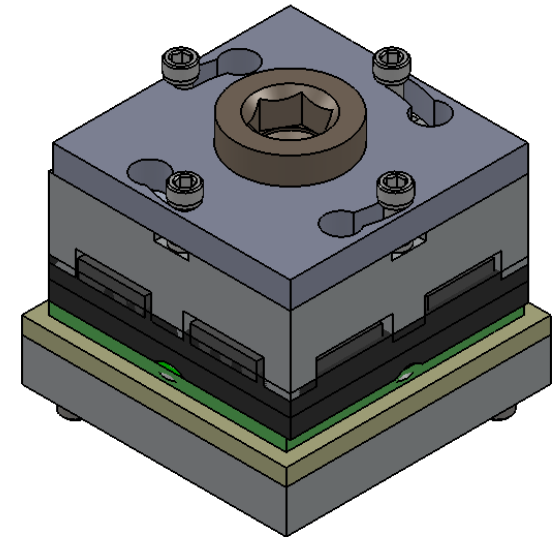


DETAIL A
SCALE 8 : 1



Features


- Wide temperature range (-55C to +180C)
- High current capability (up to 4A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time



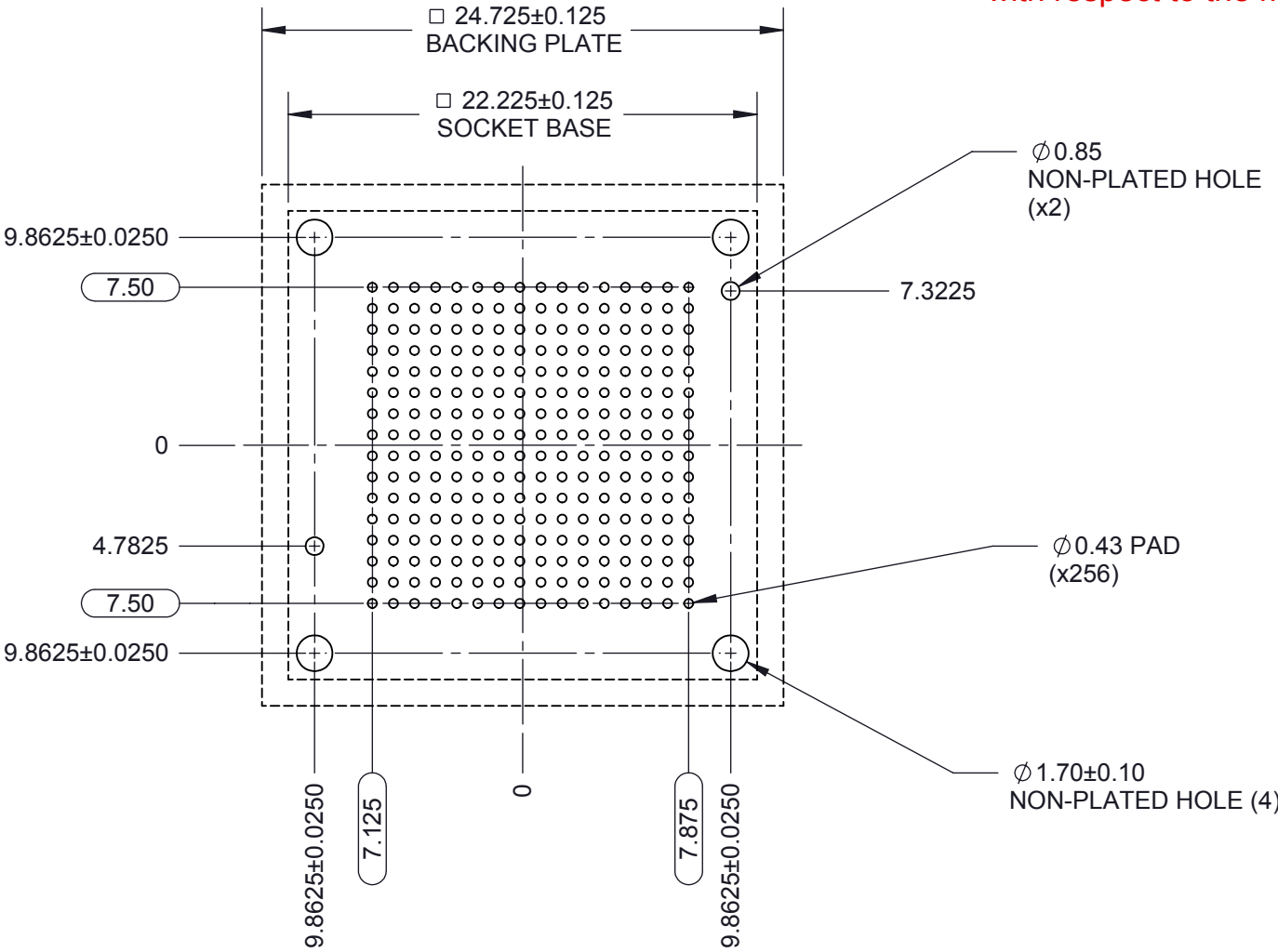
Description: Socket Spec

Primary dimension units are millimeters, Secondary dimension units are [inches]. Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001''$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001''$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005''$] unless stated otherwise. Materials and specifications are subject to change without notice.

 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: Weight: 21.08	STATUS: Released DRAWN BY: D. Hauer FILE: SBT-BGA-6006	SHEET: 1 OF 4 SCALE: 2:1 DATE: 02/12/10	REV. C


***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



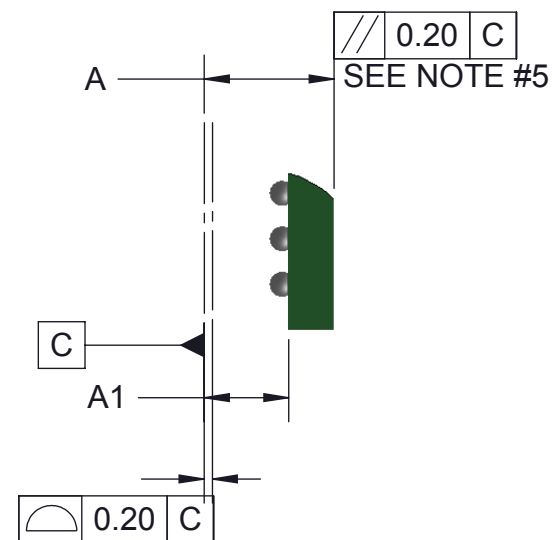
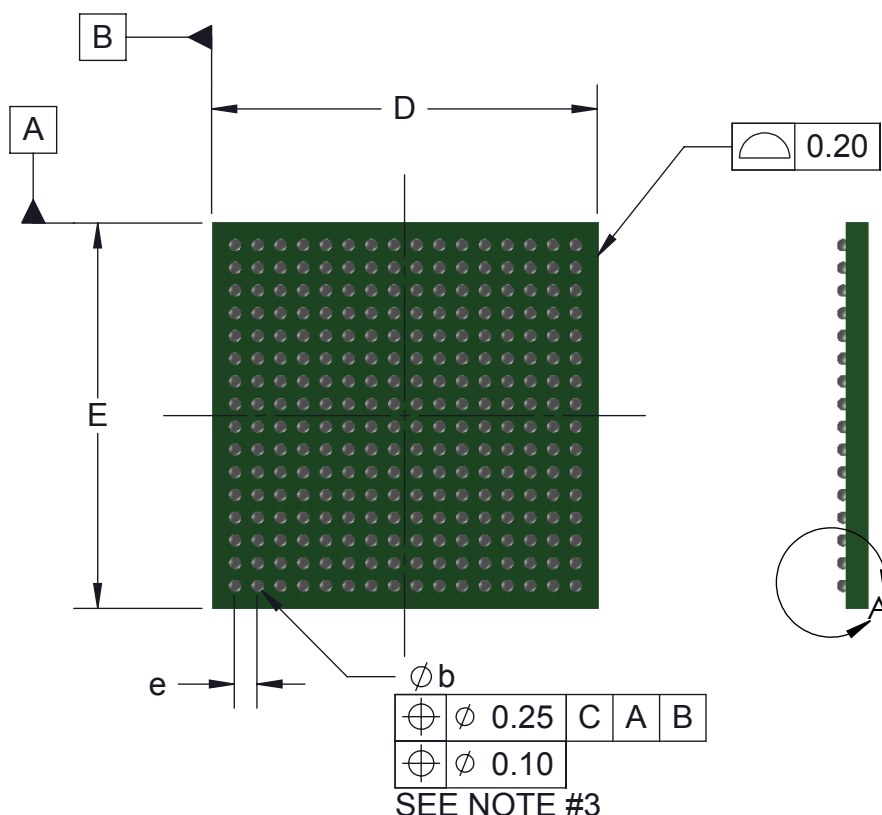
Target PCB Recommendations
 Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches]. Weight is in grams.
 Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	SBT-BGA-6006 Drawing Material: Material <not specified> Finish: Weight: 21.08	STATUS: Released DRAWN BY: D. Hauer FILE: SBT-BGA-6006	SHEET: 2 OF 4 SCALE: 3:1 DATE: 02/12/10	REV. C

IRONWOOD PACKAGE CODE: BGA256E6



DETAIL A
SCALE 6 : 1


1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum C (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

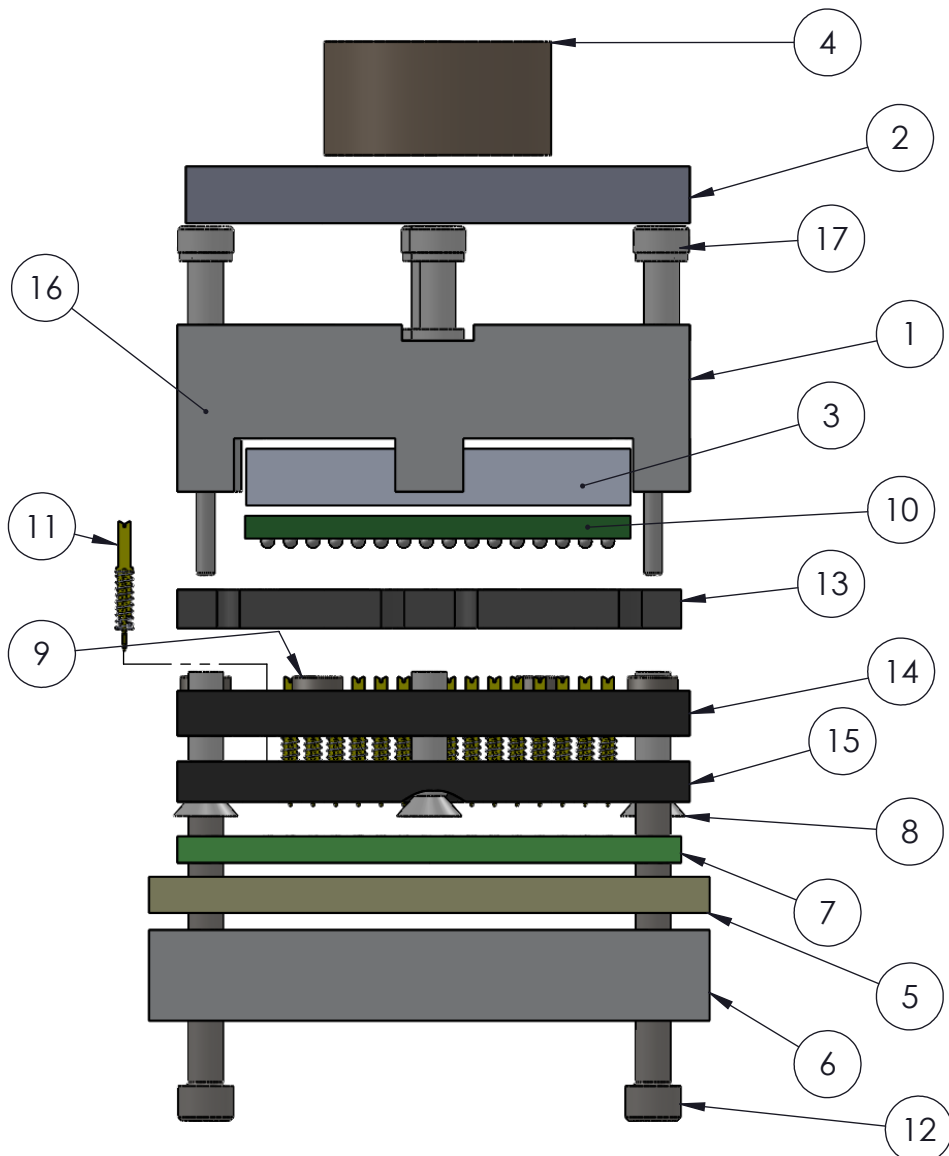
DIM	Minimum	Maximum
A		3.5
A1	0.3	0.6
b		0.7
D	17.0 BSC	
E	17.0 BSC	
e	1.00 BSC	
ARRAY SIZE	16 X 16	
PIN COUNT	256	

Description: Compatible BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

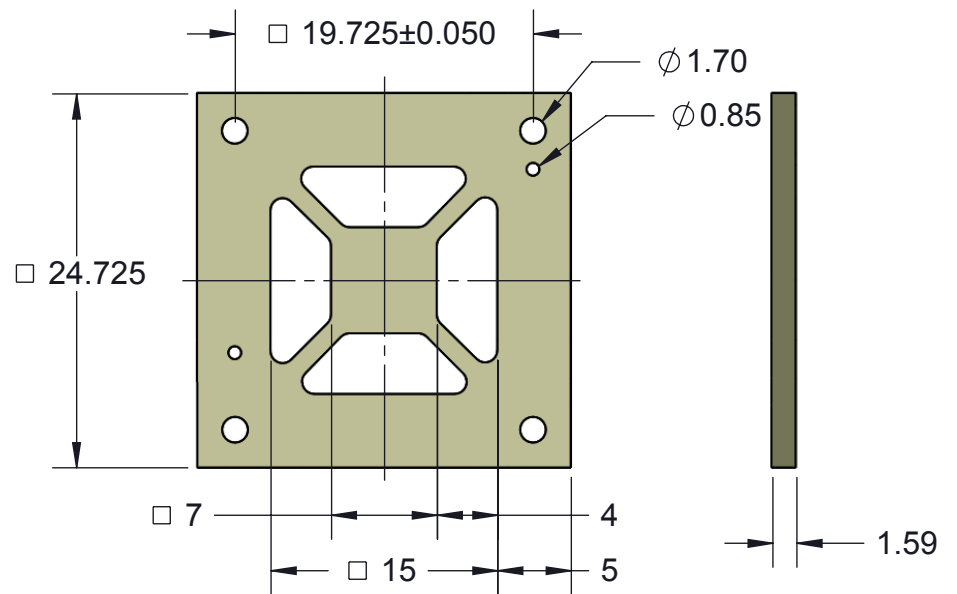
Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

 SBT-BGA-6006 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: Material <not specified> Finish: Weight: 21.08	STATUS: Released	SHEET: 3 OF 4	REV. C
		DRAWN BY: D. Hauer	SCALE: 3:1	
		FILE: SBT-BGA-6006	DATE: 02/12/10	



ITEM NO.	Description	Material
1	Socket Base, SBT BGA, 17x17	7075-T6 Aluminum Alloy
2	Socket Lid Swivel 11mm IC	7075-T6 Aluminum Alloy
3	Compression Plate	7075-T6 Aluminum Alloy
4	Compression Screw M10	7075-T6 Alumium Alloy
5	Insulation Plate	High Temp FR4
6	Backing Plate	7075-T6 Aluminum Alloy
7	TARGET PCB	High Temp FR4
8	#0-80 x .25 LG, Flat Head Machine Screw	Stainless Steel (18-8)
9	Floating Guide Spring	Alloy Steel (SS)
10	TEST CHIP	High Temp FR4
11	Pogo Pin, 1mm Pitch SBT BGA pin	
12	#0-80 x 0.5, SH Cap Screw	Material <not specified>
13	Floating Guide BGA256 1mm pitch	PEEK Ceramic filled
14	Middle Pogo Guide BGA256 1mm pitch	PEEK Ceramic filled
15	Bottom Pogo Guide BGA256 1mm pitch	PEEK Ceramic filled
16	Dowel Pin, 1/32" x 3/8", SS	Chrome Stainless Steel
17	#0-80 Shoulder Screw, 0.062" thread length	Stainless Steel (303)

SBT PIN(4:1)




INSULATION PLATE DETAIL

Description: Assembly, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches]. Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>SBT-BGA-6006 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: Material <not specified> Finish: Weight: 21.08</p>	STATUS: Released	SHEET: 4 OF 4	REV. C
		DRAWN BY: D. Hauer	SCALE: 3:1	
		FILE: SBT-BGA-6006	DATE: 02/12/10	